

# LMBR0520ET1G thru LMBR0540ET1G

## Schottky Barrier Rectifiers

Reverse Voltage 20 to 40V Forward Current 0.5A

### FEATURES

- \* Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- \* Low power loss, high efficiency
- \* For use in low voltage high frequency inverters, free wheeling, and polarity protection applications
- \* Guardring for over voltage protection
- \* High temperature soldering guaranteed: 260°C/10 seconds at terminals

### Mechanical Data

Case: SOD-323HE

molded plastic over sky die

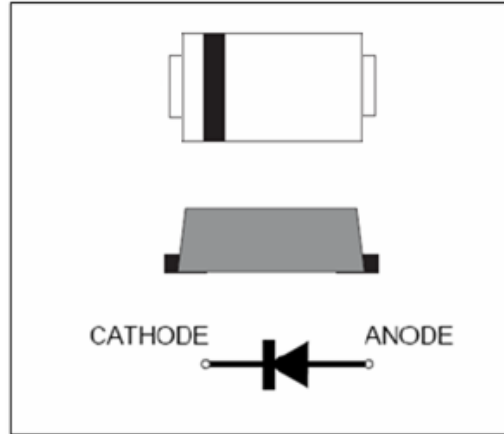
Terminals: Plated leads, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position Any

Weight 0.0053 g

Handling precaution None



We declare that the material of product is Halogen free (green epoxy compound)

### 1. Electrical Characteristic

**Maximum & Thermal Characteristics Ratings** at 25°C ambient temperature unless otherwise specified.

Parameter Symbol	symbol	LMBR0520ET1G	LMBR0530ET1G	LMBR0540ET1G	Unit
device marking code		052	053	054	
Maximum repetitive peak reverse voltage	$V_{RRM}$	20	30	40	V
Maximum RMS voltage	$V_{RMS}$	14	21	28	V
Maximum DC blocking voltage	$V_{DC}$	20	30	40	V
Maximum average forward rectified current at TC = 75°C	$I_{F(AV)}$	0.5			A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	22			A
Typical thermal resistance (Note 1)	$R_{\theta JA}$	220			°C/W
Operating junction temperature range	$T_J$	-55 to +125			°C
storage temperature range	$T_{STG}$	-55 to +150			°C

**Electrical Characteristics Ratings** at 25°C ambient temperature unless otherwise specified.

Parameter Symbol	symbol	LMBR0520ET1G	LMBR0530ET1G	LMBR0540ET1G	Unit
Maximum instantaneous forward voltage at (IF = 0.5 A, TJ = 25°C)	$V_F$	0.43	0.45	0.55	V
Maximum DC reverse current at rated DC blocking voltage $T_A = 25^\circ C$ $T_J = 100^\circ C$	$I_R$	0.25 8	0.130 10	0.03 10	mA
Typical junction capacitance at 4.0V, 1MHz	$C_J$	160			PF

NOTES:

1. 8.0mm<sup>2</sup> (.013mm thick) land areas

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## 2. Ratings and Characteristic Curves (TA = 25°C unless otherwise noted)

Fig. 1 - Forward Current Derating Curve

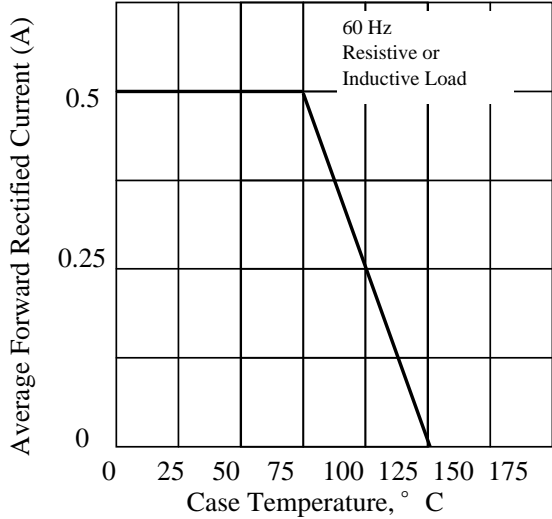


Fig. 2 - Maximum Non-repetitive Peak Forward Surge Current

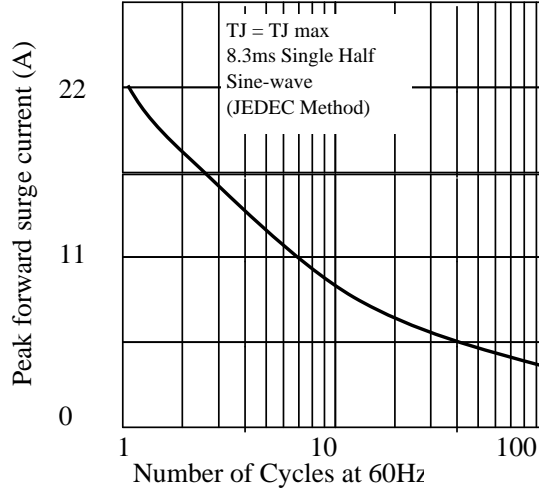


Fig 3. - Typical Instantaneous Forward Characteristics

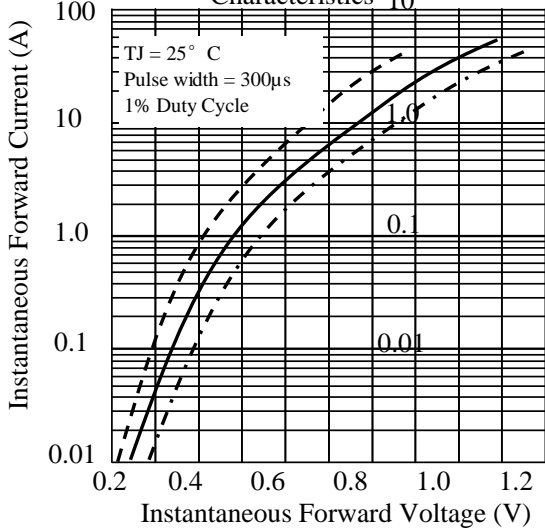


Fig 4. - Typical Reverse Characteristics

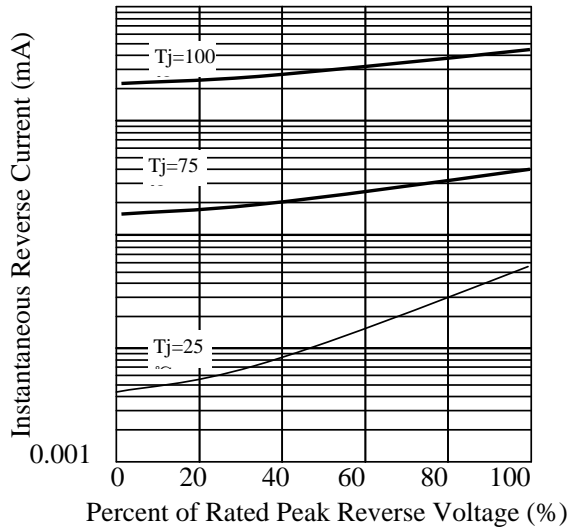


Fig 5. - typical transient thermal impedance

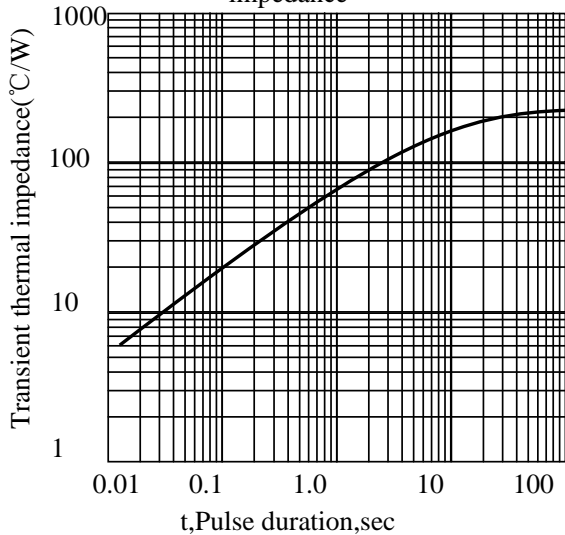
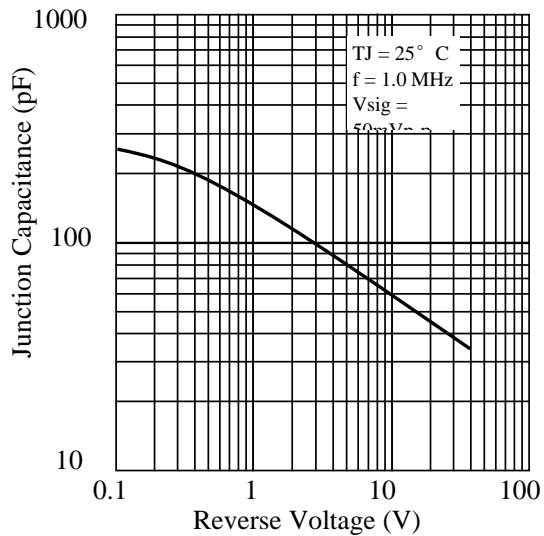


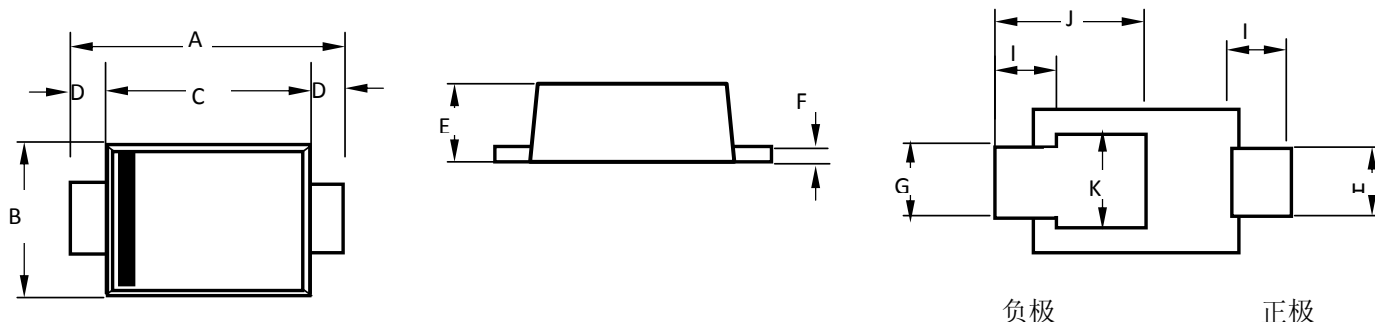
Fig 6. - Typical Junction Capacitance



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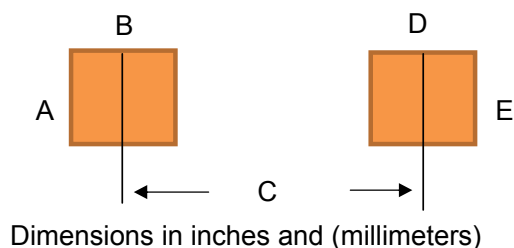
### 3. dimension:

SOD-323HE



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.30	2.70	0.091	0.106
B	1.20	1.35	0.047	0.053
C	1.75	1.95	0.069	0.077
D	0.30Typ		0.012Typ	
E	0.55	0.75	0.022	0.030
F	0.10	0.20	0.004	0.008
G	0.50	0.55	0.020	0.022
H	0.50	0.55	0.020	0.022
I	0.40	0.60	0.016	0.024
J	1.15	1.55	0.045	0.061
K	0.8Typ		0.032Typ	

Suggested solder pad layout

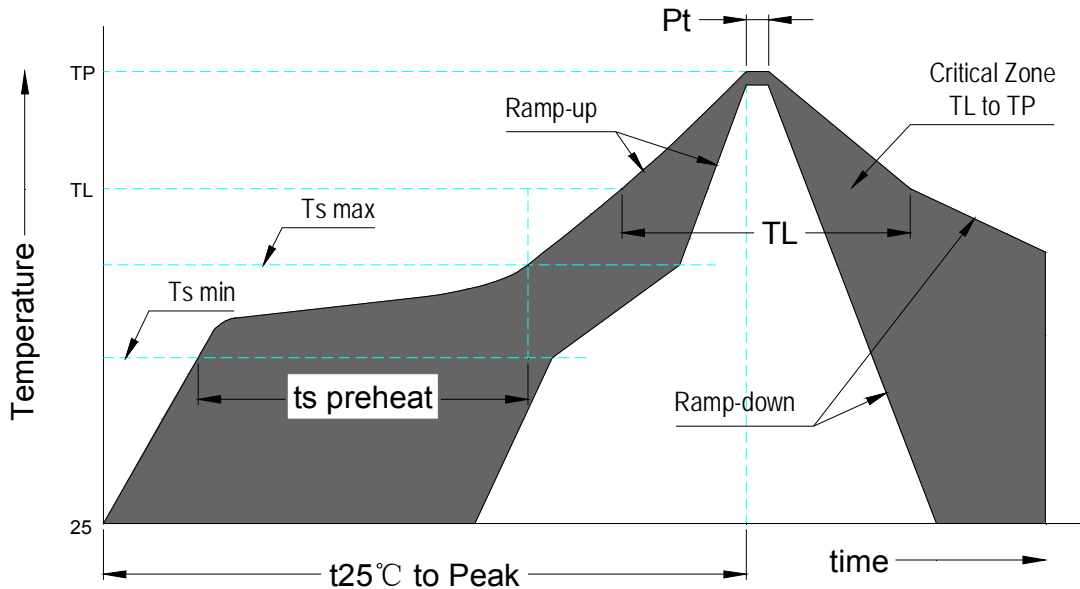


PACKAGE	A	B	C	D	E
SOD323-HE	0.032(0.8)	0.032(0.8)	0.085(2.15)	0.032(0.8)	0.032(0.8)

# LMBR0520ET1G thru LMBR0540ET1G

## 5.Suggested thermal profile for soldering process

1. Storage environment : Temperature=5~40°C Humidity=55±25%
2. Reflow soldering of surface-mount device



### 3. Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T <sub>L</sub> to T <sub>P</sub> )	<3°C/sec
Preheat	
- Temperature Min(T <sub>smin</sub> )	150°C
- Temperature Max(T <sub>smax</sub> )	200°C
- Time(min to max)(t <sub>s</sub> )	60~120sec
T <sub>smax</sub> to T <sub>L</sub>	
- Ramp-up Rate	<3sec
Time maintained above:	
- Temperature (T <sub>L</sub> )	217°C
- Time(t <sub>L</sub> )	60-260sec
Peak Temperature(T <sub>P</sub> )	255 -0/+5°C
Time within 5°C of actual Peak Temperature(T <sub>P</sub> )	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

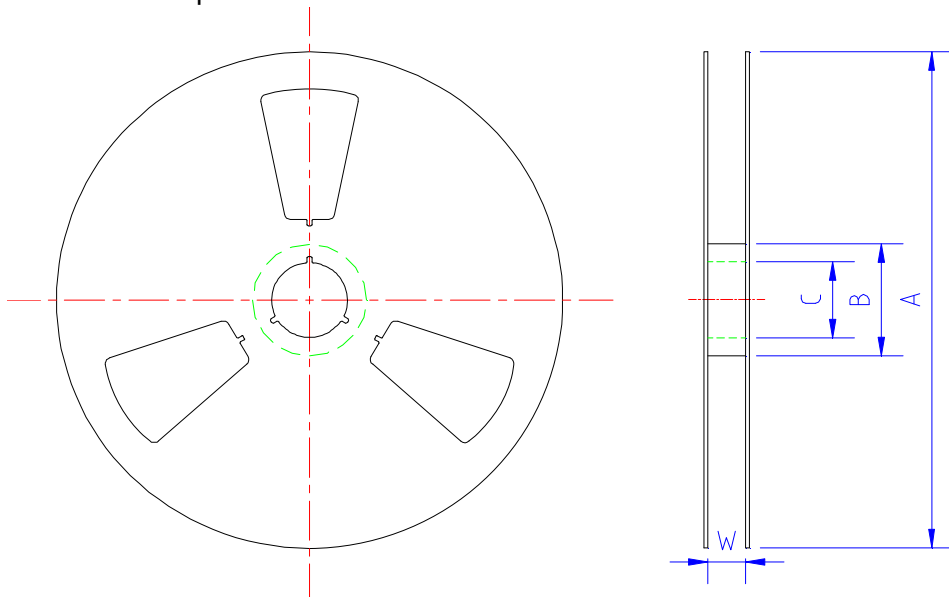
## LMBR0520ET1G thru LMBR0540ET1G

### 6.High reliability test capabilities

Item Test	Condition	Reference
Solder Resistance	at 260±5°C for 10±2sec immerse	MIL-STD-750D METHOD-2031
Solderability	at 245±5°C for 5 sec	MIL-STD-202F METHOD-208
High Temperature Reverse Bias	V <sub>R</sub> =80% rate at T <sub>j</sub> =125°C for 168hrs	MIL-STD-750D METHOD-1038
Forward Operation Life	Rated average rectifier current T <sub>A</sub> =25°C for 500hrs	MIL-STD-750D METHOD-1027
Intermittent Operation Life	T <sub>A</sub> =25°C , I <sub>F</sub> =I <sub>o</sub>	MIL-STD-750D METHOD-1036
Pressure Cooker	15P <sub>SIG</sub> at T <sub>A</sub> =121°C for 4hrs	JESD22-A102
Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. Total 10 cycles	MIL-STD-750D METHOD-1051
Thermal Shock	0°C for 5min. Rise to 100°C for 5min. Total 10 cycles	MIL-STD-750D METHOD-1056
Forward Surge	8.3ms single half sine-wave superimposed on rated load,one surge	MIL-STD-750D METHOD-4066-2
Humidity	at T <sub>A</sub> =85°C , RH=85% for 1000hrs	MIL-STD-750D METHOD-1021
High Temperature Storage Life	at 150°C for 1000hrs	MIL-STD-750D METHOD-1031

5.1 、 SMD Packing Reel Spec & Packing Quantity

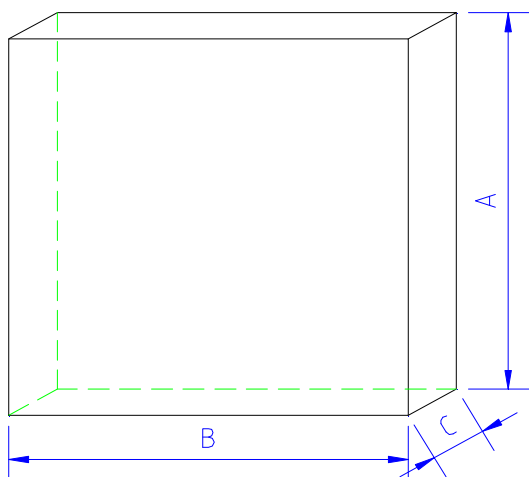
5.1.1 Reel Packing  
A. Reel Spec



unit: mm

SPEC	A	B	C	W	Quantity/Reel
SMA-FL 7" reel	177.0±2.0	54.0±0.5	13.0±0.5	13.2±0.2	3K
TO277 13" reel	330.0±2.0	75.0±0.5	13.0±0.5	13.2±0.2	5K
SOD123FL 7" reel	177.0±2.0	50.0±0.5	13.0±0.5	9.4±1.5	3K
SOD323HE 7" reel	177.0±2.0	50.0±0.5	13.0±0.5	9.4±1.5	3K
SMB-FL 13" reel	330.0±2.0	75.0±0.5	13.0±0.5	13.2±0.2	5K

B. 13" reel packing box



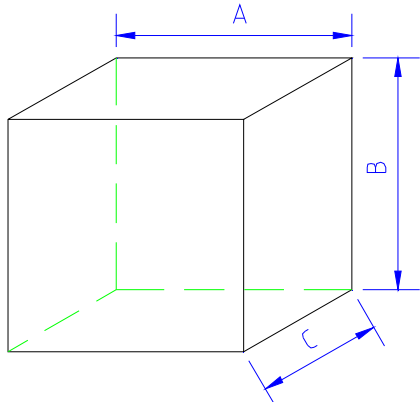
unit: mm

size	A	B	C
	335±5.0	335±2.0	40±1.0

as per above packing

Spec	Q' ty/Box
TO277 13" reel	10K
SMB-FL 13" reel	10K

C. 7" reel packing box



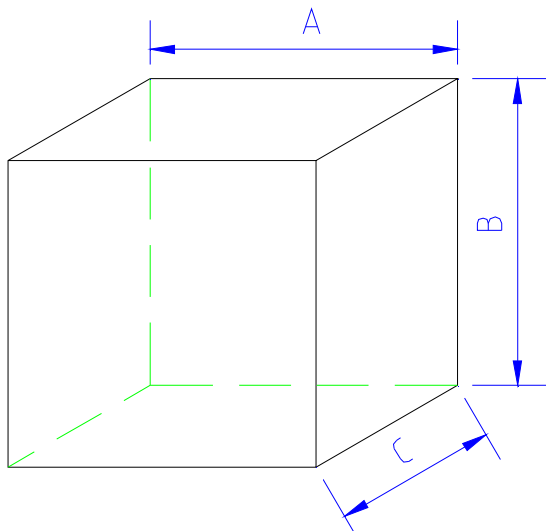
unit: mm

	A	B	C
SMA-FL SOD123FL SOD323HE	186±2.0	139±2.0	185±2.0

as per above packing

	Q' ty/Box
SMA-FL	30K
SOD123FL	30K
SOD323HE	30K

D. reel packing carton



unit: mm

	A	B	C
size	350±2.0	340±2.0	350±2.0

as per above packing

Spec	Q' ty/Carton
TO277 13" reel	80K
SMB-FL 13" reel	80K

unit: mm

	A	B	C
SMA-FL SOD123FL SOD323HE	455±2.0	400±2.0	410±2.0

as per above packing

Spec	Q' ty/Carton
SMA-FL 7" reel	360K
SOD123-FL 7" reel	360K
SOD323HE 7" reel	360K

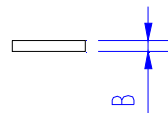
5.1.2 Tape Spec

A. Cover Tape

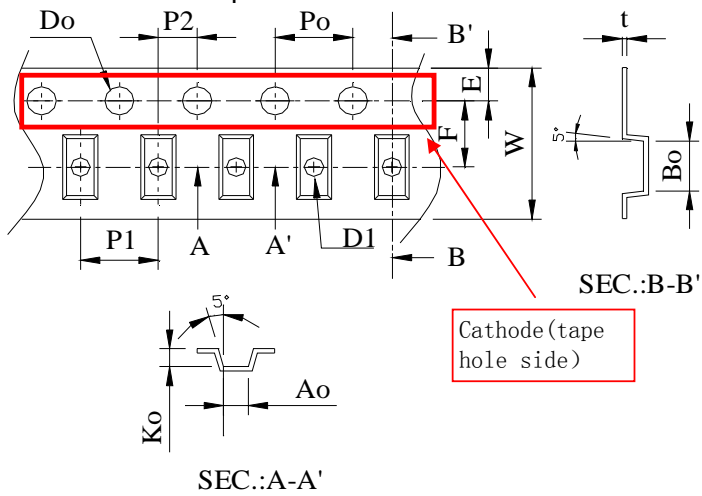


unit: mm

	A	B
SMA-FL SMB-FL TO277	9.5±0.10	0.062±0.007
SOD123FL SOD323HE	5.4±0.10	



**B. Carrier Tape**

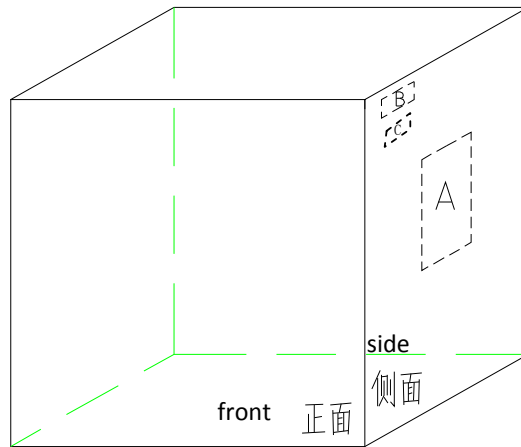
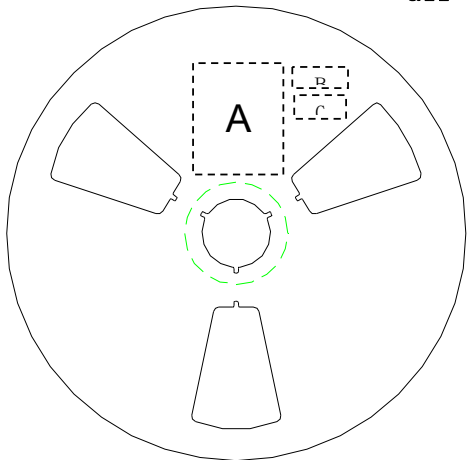


Item	SOD323HE	SOD123FL	SMA-FL	SMB-FL	TO277
W	8±0.3	8±0.3	12±0.3	12±0.3	12±0.3
P1	4±0.1	4±0.1	4±0.1	8±0.1	8±0.1
E	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1
F	3.5±0.05	3.5±0.05	5.5±0.05	5.5±0.05	5.5±0.05
D0	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05
D1	1.1±0.1	1.1±0.1	1.5±0.1	1.55±0.05	1.5±0.1
P0	4±0.1	4±0.1	4±0.1	4±0.1	4±0.1
P2	2±0.05	2±0.05	2±0.05	2±0.05	2±0.05
10P0	40±0.2	40±0.2	40±0.2	40±0.2	40±0.2
A0	1.45±0.1	1.95±0.1	2.83±0.1	3.8±0.1	4.3±0.1
B0	2.75±0.1	3.95±0.1	4.75±0.1	5.75±0.1	6.8±0.1
K0	0.80±0.1	1.30±0.1	1.42±0.1	1.4±0.1	1.35±0.1
T	0.25±0.05	0.25±0.05	0.25±0.05	0.25±0.05	0.25±0.05



5.2、SMD Power Diode General Packing Spec

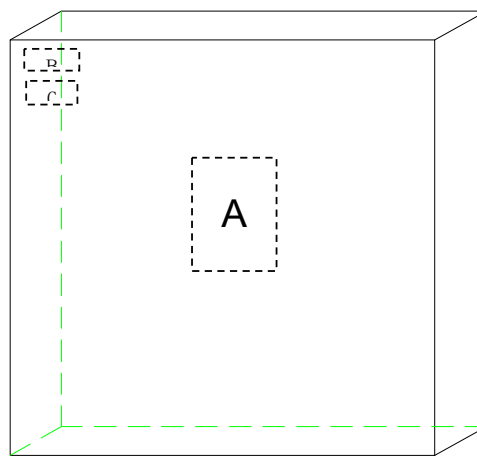
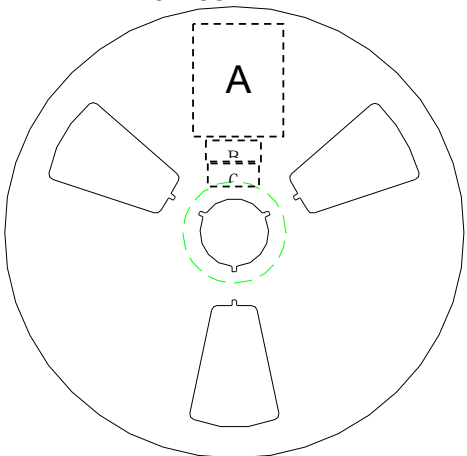
A. 7" reel all labels will be at cathode side of reel ;



A:LRC label;

B:Environment Label C:Halide free label

B. 13" reel



A:LRC label;

B:Environment Labe C:Halide free label

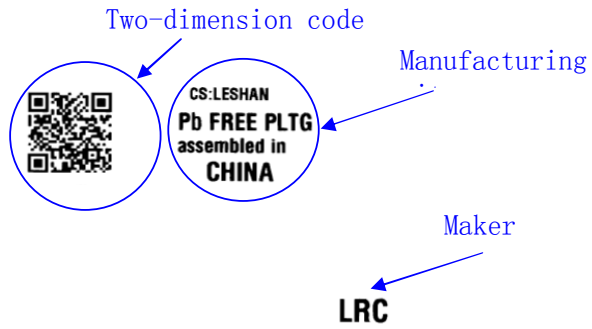
C. Tape lead: face anode side of the reel, upper side is the tape lead position. All labels are at cathode side of the reel.



标题: <b>Power Diode SMD Package Packing Spec</b>	DOC NO.: WI-258
	Version: 5    Modification: 0
	Page: 6

C. Label Content :  
LRC Label

P/N → (1P) LPN: **SM140A**  
 Lot No. → (1T) LOT: **140106049X**  
 Date code → (9D) DTE: **1403**  
 Quantity → (Q) QTY: **10000**



lot: 140106049X: 140106---2014/1/6; 049----lot number:49; X: product code

Environment Label



Halide-free Label



## LMBR0520ET1G thru LMBR0540ET1G

### 7. Update Record

版次	更新记录	更新作者	更新日期
1	第一版	周杰	2014.02.26
2	修正产品引脚G尺寸, 由0.75~0.95mm为0.50~0.55mm	周杰	2014.07.18